Product Change Notification

108732 - 03

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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Product Change Notification

Change Notification #:	**108732 - 03**
Change Title:	**Intel(R) Compute Module MFS5000SI, PCN 108732-03, Product Design, Adding Dual Footprint for Trusted Platform Module (TPM) Component and Improving Front Side Bus (FSB) Routing, Reason for Revision: Revision of Projected Implementation Date**
Date of Publication:	**January 12, 2009**

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Mar 27, 2009

Description of Change to the Customer:

Reason for Revision: Revision of Projected Implementation Date

Intel is adding a dual footprint for the TPM component in order to allow flexibility in the selection and execution of the TPM part. In addition, Intel is implementing a printed circuit board (PCB) change to improve the Front Side Bus (FSB) routing for the secondary processor. This design change will result in better signal quality. Also updating the installed FW revision to P2.6.

Customer Impact of Change and Recommended Action:

No customer impact is being projected. However, standard compute module validation testing is highly recommended.

Products Affected / Intel Ordering Codes:

Pre Change Product Code	Pre Change MM#	Pre Change TA	Pre Change PBA	Post Change MM#	Post Change TA	Post Change PBA
MFS5000SI 892778	892778	91952-005	70726-405	900409	91952-006	D70726-501
MFS5000SIB 892856	892856	19099-002	70726-405	900410	19099-003	D70726-501

Reference Documents / Attachments:

Document: **Location #:**

PCN Revision History:

Date of Revision:	**Revision Number:**	**Reason:**
August 18, 2008	00	Originally Published PCN
November 17, 2008	01	Updating with FW revision
November 19, 2008	02	Correction to Compute Module TA Revision Number
January 12, 2009	03	Revision of Projected Implementation Date